

L Number	Hits	Search Text	DB	Time stamp
1	0	duplexer same advan\$4	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 15:55
3	4	(duplexer same advan\$4) and (wireless adj system)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 15:56
2	448	duplexer same advan\$4	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:03
4	2	("5578525").PN.	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:08
5	14	("4233620" "4264917" "4633573" "4721945" "4769272" "4835120" "4901136" "5102829" "5206188" "5309021" "5342807" "5357400" "5474957" "5519936").PN.	USPAT	2003/12/13 16:04
6	23	5578525.URPN.	USPAT	2003/12/13 16:09
7	0	(437/206).CCLS.	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:08
8	0	(437/206).CCLS.	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:09
9	1021	(257/704).CCLS.	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:24
10	8859	solder adj ball	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:28
11	8437	solder adj paste	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:28
12	1033	(solder adj ball) and (solder adj paste)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 17:34
13	167195	PCB or (printed adj circuit adj board)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:30
14	3525645	(PCB or (printed adj circuit adj board)) ad opening	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:30
15	167195	(PCB or (printed adj circuit adj board)) and ((PCB or (printed adj circuit adj board)) ad opening)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:30
16	697	((solder adj ball) and (solder adj paste)) and ((PCB or (printed adj circuit adj board)) ad opening)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:30
17	245	((((solder adj ball) and (solder adj paste)) and ((PCB or (printed adj circuit adj board)) ad opening)) and carrier	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:41

18	1983	signal adj trace	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:42
19	834	signal adj skew	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:42
20	7	(signal adj trace) and (signal adj skew)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:45
21	2	("5983493" "6194778").PN.	USPAT	2003/12/13 16:44
22	138656	multilayer	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:45
23	3048	multilayer adj substrate	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:46
24	2	(multilayer adj substrate) and (signal adj skew)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:47
25	16	multilayer and (signal adj skew)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:47
26	32	("3930857" "4604644" "4814943" "5121190" "5128746" "5136365" "5194930" "5216278" "5218234" "5227008" "5261155" "5355283" "5357673" "5371404" "5398863" "5401913" "5436503" "5442240" "5450283" "5489749" "5536909" "5550408" "5583376" "5583378" "5601678" "5647123" "5650593" "5663530" "5686703" "5717252" "5744863" "5801449").PN.	USPAT	2003/12/13 16:55
27	155	((solder adj ball) and (solder adj paste)) and (melting adj temperature)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 17:34
28	16	174/250-268.ccls. and (((solder adj ball) and (solder adj paste)) and (melting adj temperature))	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 17:37
29	17	361/760-795.ccls. and (((solder adj ball) and (solder adj paste)) and (melting adj temperature))	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 17:37
30	12	("4882454" "5072075" "5121190" "5483421" "5574630" "5615087" "5661089" "5798563" "5894173" "5900675" "5926377" "5982630").PN.	USPAT	2003/12/13 17:37